



MANAGEMENT SYSTEM CERTIFICATE

Certificate No:
1528-2000-AE-RGC-RvA

Initial certification date:
01 March, 2000

Valid:
02 March, 2024 – 01 March, 2027

This is to certify that the management system of

Shanghai Seefull Electronic Co., Ltd.

6 Zhen Ye Rd, Dongjing Industrial Area, Songjiang District, Shanghai, China
and the sites as mentioned in the appendix accompanying this certificate

has been found to conform to the Environmental Management System standard:
ISO 14001:2015

This certificate is valid for the following scope:

**Design and Manufacture of Diodes, To-Bridge, Bridge Rectifiers, Wafer FAB,
Surface Mounted Devices (SMD) and OPTO.**

Manufacture of CIS (Contact Image Sensor), and Manufacture of 4" Wafer

Place and date:
Shanghai, 20 February, 2024

For the issuing office:
**DNV - Business Assurance
Suite A, Building 9, No.1591 Hongqiao
Road, Changning District, Shanghai
200336, P.R. China
TEL: +86 21 32799000**



Zhu Hai Ming
Management Representative

Lack of fulfilment of conditions as set out in the Certification Agreement may render this Certificate invalid.

ACCREDITED UNIT: DNV Business Assurance B.V., Zwolseweg 1, 2994 LB, Barendrecht, Netherlands - TEL: +31(0)102922689. www.dnv.com/assurance



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Appendix to Certificate

Shanghai Seefull Electronic Co., Ltd.

Locations included in the certification are as follows:

| Site Name | Site Address | Site Scope |
|---|---|---|
| Shanghai Seefull Electronic Co., Ltd. | 6 Zhen Ye Rd, Dongjing Industrial Area, Songjiang District, Shanghai, China | Design and Manufacture of Diodes, To-Bridge, Bridge Rectifiers, Wafer FAB, Surface Mounted Devices (SMD) and OPTO |
| Lite-On Microelectronics (Wuxi) Co., Ltd. | Land Lot J7-J8WEPZ, Wuxi, Jiangsu, China | Design and Manufacture of To-Bridge, Bridge Rectifiers, Surface Mounted Devices (SMD) and OPTO |
| Lite-On Semiconductor (Wuxi) Co., Ltd. | No. 45, Zhujiang Road, New District, Wuxi City, Jiangsu, China | Manufacture of CIS (Contact Image Sensor), and Manufacture of 4" Wafer |